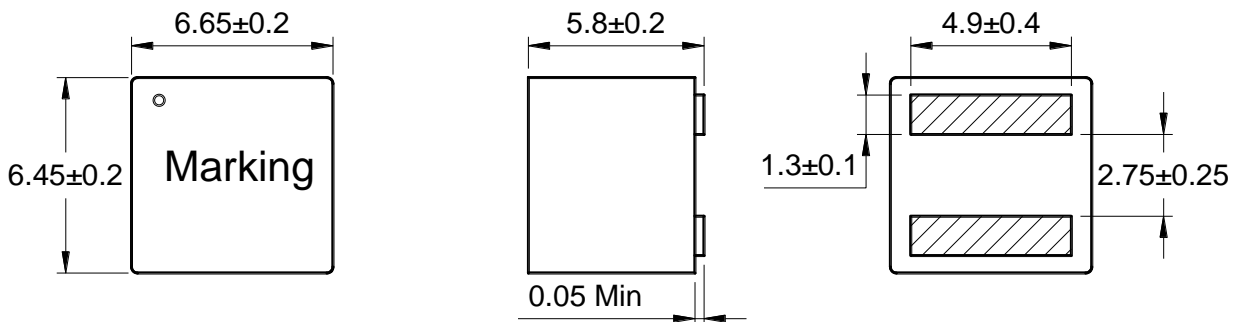


Outline: 产品概要

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI).
磁屏蔽结构：抗电磁干扰(EMI)性能强。
- A composite structure, ultra low buzz noise.
一体成型结构，超低蜂鸣噪音。
- Low loss, high efficiency, wide application frequency.
低损耗，高效率，应用频率宽。
- Lightweight design, save space, suitable for high density SMT.
轻薄型设计，节省空间，适合高密度贴装。
- Die-casting by low loss alloy powder: low impedance, small parasitic capacitance.
低损耗合金粉末压铸：低阻抗，寄生电容小。
- Operating temperature : -40°C ~ +125°C (Including coil's temperature rise)
工作温度：-40°C ~ +125°C (包含线圈发热)

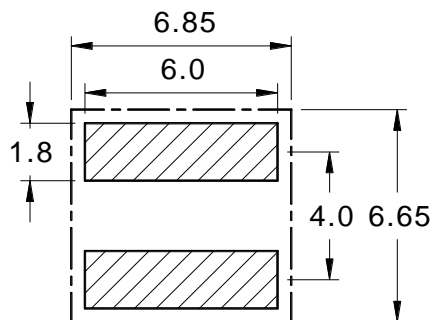
1 Appearance and dimensions (mm) 外形尺寸



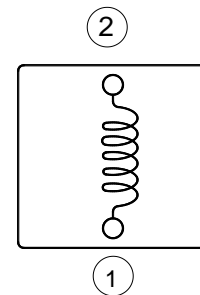
2 Marking 印字标识



3 Reference land pattern (mm) 参考基板尺寸



4 Schematic 原理图



5 Electrical characteristics

电气特性

Part No. 品名	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
CSEB0660-4R7M	4.70	13.0	15.0	10.5	11.0
CSEB0660-5R6M	5.60	15.0	17.3	10.0	10.0
CSEB0660-6R8M	6.80	17.6	20.2	9.20	9.00
CSEB0660-8R2M	8.20	23.0	26.5	8.40	8.00
CSEB0660-100M	10.0	26.5	30.5	7.60	7.00
CSEB0660-150M	15.0	42.0	48.3	6.00	5.50
CSEB0660-220M	22.0	55.1	63.4	5.60	5.00

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C条件下测试。

※1 Inductance measure condition at 100kHz, 0.1V.

电感测试条件为 100kHz, 0.1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 30% of its initial value.

饱和电流: 电感值下降其初始值的 30%时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).

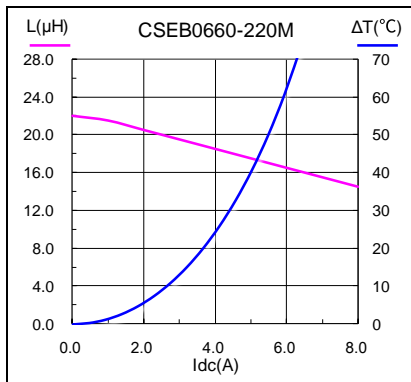
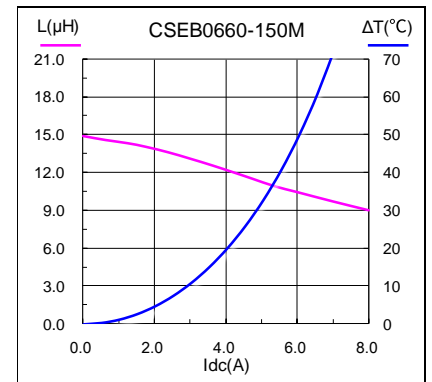
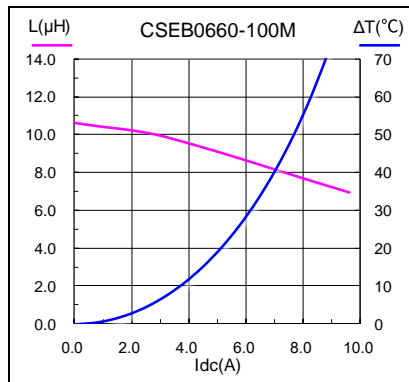
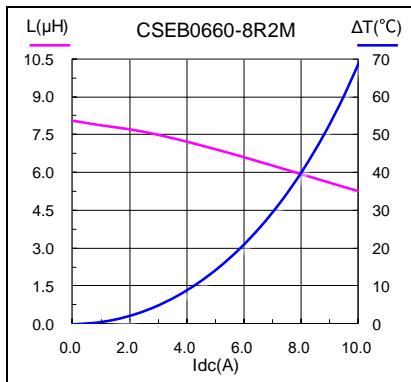
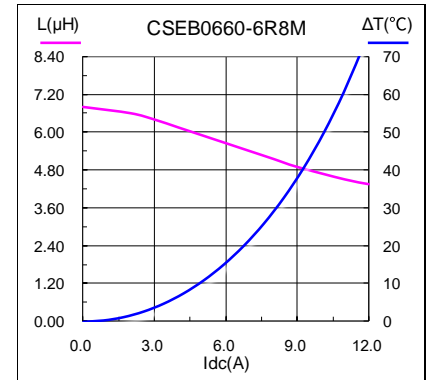
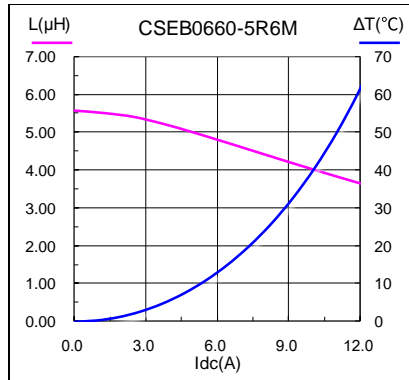
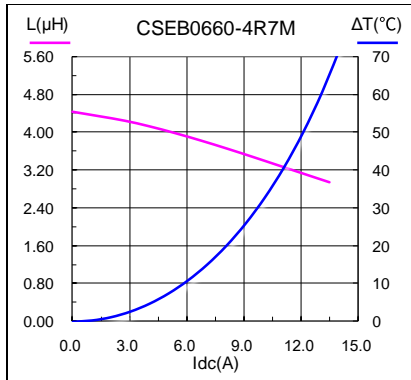
温升电流: 使产品温度上升到 ΔT40°C时所加载的实际直流电流值(Ta=25°C)。

※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷线路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。

**6 Saturation current VS temperature rise current curve
饱和电流 VS 温升电流曲线**

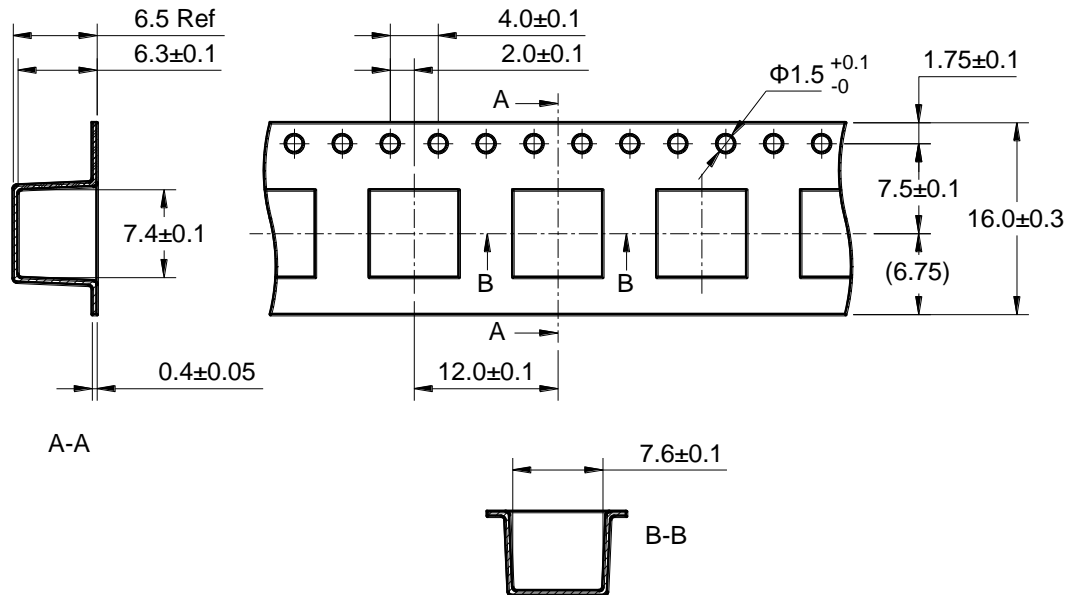


7 Packing specification

包装规格

7.1 Carrier tape dimensions (mm)

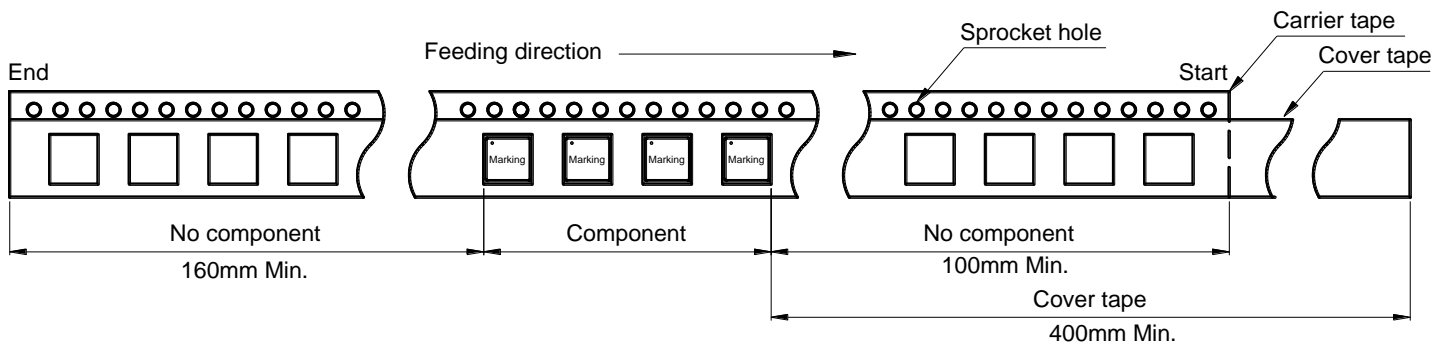
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape direction

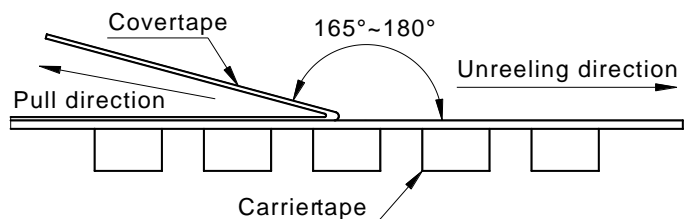
捆包方向



7.3 Cover tape peel off condition

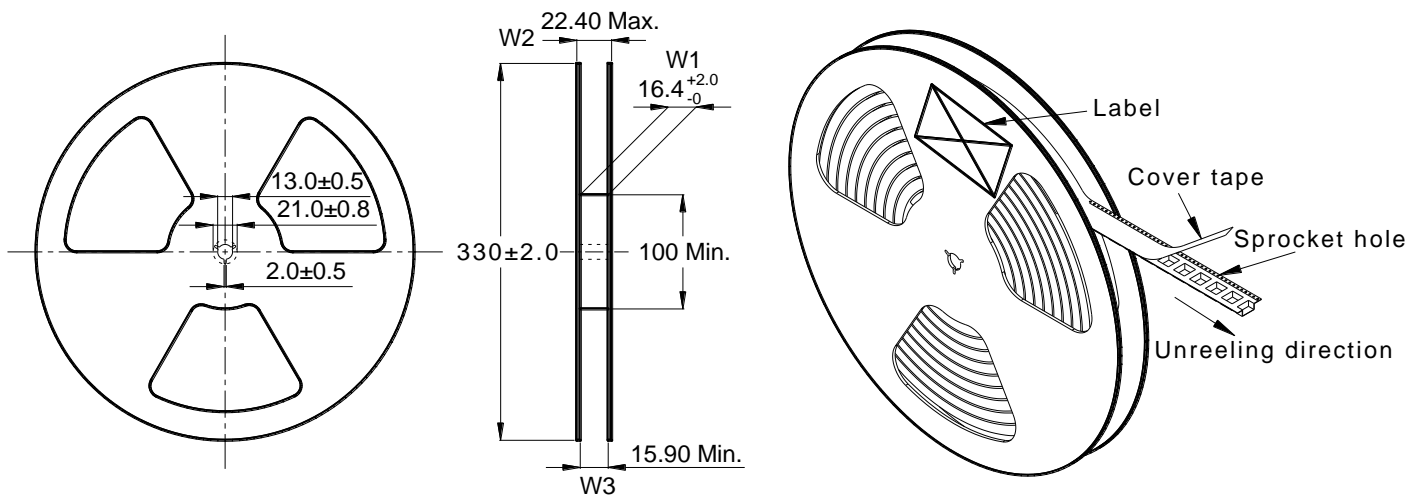
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1~1.3N。
- Reference peel speed $300 \pm 10\text{mm/min.}$
参考剥离速度 $300 \pm 10\text{mm/分钟.}$



7.4 Reel dimensions (mm)

卷盘尺寸



7.5 Carton dimensions and packing quantity

包装箱尺寸和包装数量

■ Inner Carton: 340×340×95mm
内包装盒

■ Out Carton : 355×355×385mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
CSEB0660	700pcs	(700×3) = 2100pcs	(2100×3) = 6300pcs

7.6 Label making

标签标识

The following items will be marked on the reel of product label and shipping label.

以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label

产品标签

- Part No.
产品型号
- Electrical Information
产品电性信息
- Quantity
数量
- Packing No.
包装流水号

Shipping Label

运输标签

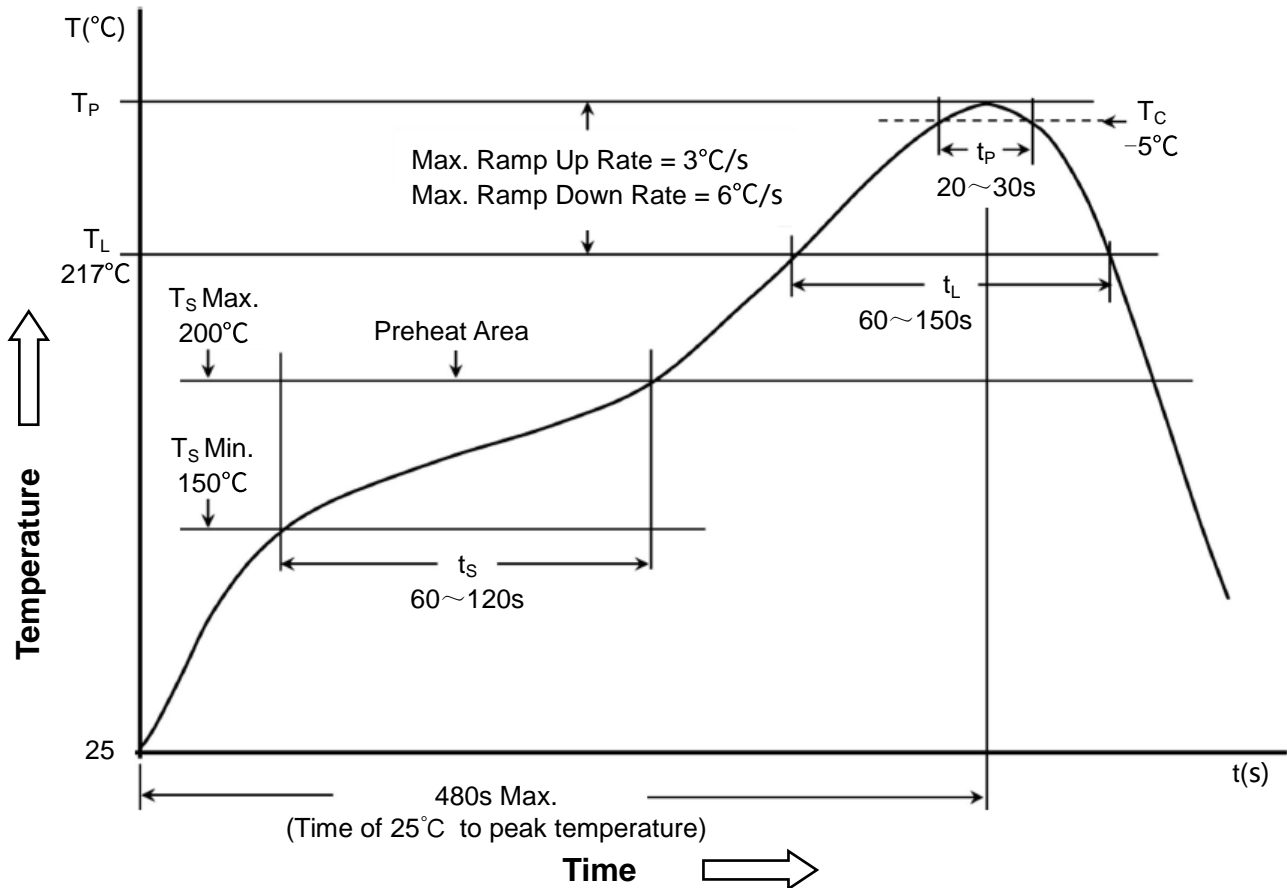
- Customer Name
客户名称
- Customer Part No.
客户型号
- Supplier Part No.
供应商型号
- Supplier Name
供应商名称
- Country of origin
产品产地

8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D。